EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	73	(murakami-keiichi).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2007/12/15 00:34
S2	4	(murakami-keiichi).in. and (printed adj wiring adj board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2008/02/21 17:59
S3	4	("20050258522" | "20060037193" | "20060115582" | "6739040").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/21 18:09
S4	5	("3956041" | "5057372" | "5344893" | "5346750" | "6376053").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/23 22:24
S5	6	("3989767" | "4504607" | "4752499" | "5021472" | "5055321" | "5137936").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/23 22:37
S6	57	("5055321").URPN.	USPAT	OR	OFF	2008/02/23 22:45
S7	12	("4752499" | "5021472" | "5055321" | "5344893" | "5447996" | "5519177" | "5589255" | "5688583" | "5741575" | "5795618" | "5921472" | "6010768").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/23 23:12
S8	8	("6248428").URPN.	USPAT	OR	OFF	2008/02/23 23:13
S9	202	(pcb or ((circuit or wiring) adj board)) and (press$3 with resin) and (cur$3 with resin) and (polish$3 with resin)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/23 23:17
S10	101	(pcb or ((circuit or wiring) adj board)) and (press$3 with resin) and (cur$3 with resin) same (polish$3 with resin)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/23 23:17
S11	15	(pcb or ((circuit or wiring) adj board)) and (press$3 with resin) same (cur$3 with resin) same (polish$3 with resin)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/23 23:17
S12	14	(pcb or ((circuit or wiring) adj board)) and (press$3 with resin) and (polish$3 with resin) and pressing adj plate	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 22:42

S15	18	(pcb or ((circuit or wiring) adj board)) and (press$3 with prepreg) and (pressing adj plate)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 22:48
S16	8	("3884771").URPN.	USPAT	OR	OFF	2008/02/24 22:50
S17	1	(pcb or ((circuit or wiring) adj board)) and (press$3 with heat $3) and (pressing adj plate) near4 nickel	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 22:52
S21	504	(pcb or ((circuit or wiring) adj board)) and (press$3 with heat $3 with prepreg) with (laminat $3)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 22:54
S22	197	(pcb or ((circuit or wiring) adj board)) and (press$3 with heat $3 with prepreg) with (laminat $3) and nickel	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 22:55
S23	18	(pcb or ((circuit or wiring) adj board)) and (press$3 with heat $3 with nickel) with (laminat$3)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 23:03
S24	105	(pcb or ((circuit or wiring) adj board)) and (press$3 with heat $3 with nickel)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 23:03
S25	6	("4541894" | "5450290" | "5484647" | "5525402" | "5600103" | "5766670").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/24 23:10
S26	45	(pcb or ((circuit or wiring) adj board)) and ((press$3 with heat $3) same (nickel near2 (foil or plate or sheet)))	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 23:15
S27	12	(pcb or ((circuit or wiring) adj board)) and ((press$3 near6 heat$3) with (nickel near2 (foil or plate or sheet)))	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/24 23:32
S29	32	(29/847,830,831,846).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin) and (polish$3 with resin)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:20
S32	13	(29/847,830,831,846).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:24
S34	13	(29/847,830,831,846).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:26

S35	1	(156/295,285).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:30
S36	10	(174/255,258).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:30
S37	2	(257/678,688).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/02/26 22:32
S38	4	(murakami-keiichi).in. and (printed adj wiring adj board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2008/02/28 11:59
S39	4	("20050258522" | "20060037193" | "20060115582" | "6739040"). PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/02/28 12:34
S40	12	("4574371" | "4752499" | "4927983" | "5021472" | "5055321" | "5227012" | "5344893" | "5447996" | "5519177" | "5589255" | "5688583" | "5741575").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/01 23:18
S41	14	("6010768").URPN.	USPAT	OR	OFF	2008/03/01 23:18
S42	4	(murakami-keiichi).in. and (printed adj wiring adj board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2008/03/01 23:19
S43	13	(29/847,830,831,846).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/03/01 23:20
S44	1	(156/295,285).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/03/01 23:20

S45	2	(257/678,688).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2008/03/01 23:20
S46	1	("6268648").PN.	USPAT; USOCR	OR	OFF	2008/03/01 23:21
S47	1	("5574309").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/01 23:21
S48	29	("6268648").URPN.	USPAT	OR	OFF	2008/03/01 23:21
S49	2	("6010768" | "6268648").PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	ON	2009/02/01 13:25
S50	4	(murakami-keiichi).in. and (printed adj wiring adj board)	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	ON	2009/02/02 00:04
S51	15	(29/847,830,831,846).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2009/02/02 00:07
S52	1	(156/295,285).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2009/02/02 00:09
S53	2	(257/678,688).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2009/02/02 00:09
S54	4	resin with ((non adj (cure or cured or curable or curing)) near3 temperature) with (range or between or from or window)	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/17 11:41
S55	8	(epoxy or resin or resinous or resinuous) same ((non adj (cure or cured or curable or curing)) near3 temperature) same (range or between or from or window)	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/17 11:43

S56	10	(murakami near keiichi).in. and (printed adj wiring adj board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/12/18 00:52
S57	16	(29/847,830,831,846).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; USOCR	OR	OFF	2009/12/18 00:57
S58	1	(156/295,285).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; USOCR	OR	OFF	2009/12/18 00:58
S59	2	(257/678,688).ccls. and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; USOCR	OR	OFF	2009/12/18 01:00
S60	45	(resin with temperature with press$3) and (pcb or ((circuit or wiring) adj board)) and (press$3 with resin with (circuit$4 or wiring or conductor or trace or line)) and (polish$3 with resin) and cur$3	US-PGPUB; USPAT; USOCR	OR	OFF	2009/12/18 01:02

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